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To the Honorable Commissioner of Pa.

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original documents or copy thereof.

j-525 U.S. PTO  
09/237787

01/26/99

## 1. Name of conveying party(ies):

**KUN-CHIH WANG, MING-SHENG YANG,  
WEN-YI HSIEH**Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

## 2. Name and address of receiving party(ies):

Name: **UNITED MICROELECTRONICS CORP.**

Internal Address:

Street Address: **No. 3, Li-Hsin Rd. II,  
Science-Based Industrial Park  
Hsinchu, Taiwan, R.O.C.**

City: State: ZIP:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other

Execution Date: January 12, 1999

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: January 12, 1999

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **ERIC S. HYMAN**

Internal Address:

**BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN**Street Address: **12400 Wilshire Boulevard  
Seventh Floor**City: **Los Angeles** State: **CA** ZIP: **90025**6. Total number of applications and patents involved: **1**

## 7. Total fee (37 CFR 3.41) .....\$40.00

☒ Enclosed☒ Authorized to be charged to deposit account8. Deposit account number: **02-2666**

(Attach duplicate copy of this page if paying by deposit account)

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## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.***ERIC S. HYMAN, ESQ. REG. NO. 30,139**

Name of Person Signing, Reg. No.

Signature

Date

Total number of pages including cover sheet, attachments &amp; document: \_\_\_\_\_

# ASSIGNMENT

WHEREAS,

1. Kun-Chih Wang
3. Wen-Yi Hsieh

2. Ming-Sheng Yang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD FOR FABRICATING METAL INTERCONNECT STRUCTURE**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.

of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Kun-chih Wang  
Signature:  
Sole or First Joint Inventor: Kun-Chih Wang

Jan. 12, 1999  
Date:

Ming Sheng Yang  
Signature:  
Second Joint Inventor (if any): Ming-Sheng Yang

Jan. 12, 1999  
Date:

Wen-Yi Hsieh  
Signature:  
Third Joint Inventor (if any): Wen-Yi Hsieh

Jan. 12, 1999  
Date: